

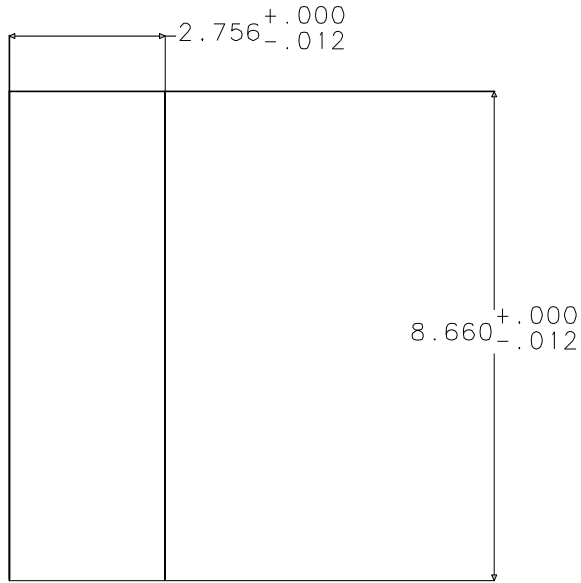
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Dwg. NO. 2708

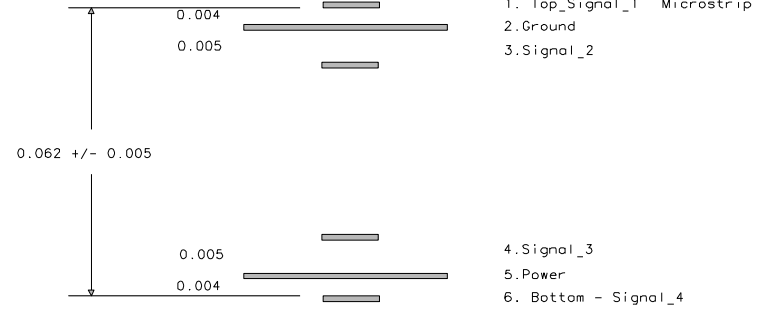
SH REV. A

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Top - Comp.Side

Layer Order



Board Characteristics - 6 LAYER BOARD

- All dimensions are given in inches unless specified otherwise.
- Material FR4 $T_g > 170C$.
- General trace width/clearance on all layers is 5 mils.
- 1/2 oz Copper for all signal layers; 1oz Copper for planes.
- Immersion Gold over copper, with min. Ni: 2.5-5 um; Au: 0.05-0.2 um.
- Apply Solder Mask over bare copper.
- Silkscreen on Component and Solder Sides.
- FHS tolerances: +/- 0.003 unless specified otherwise.
- Interlayer spacing as specified
- Impedance control: 50 Ohm +/- 10% on all 5 mil traces, inner and outer layers.

BOARD'S DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
○	.008	1734	YES	---	
⊞	.032	40	YES	---	
⊙	.041	38	YES	---	
⊞	.094	2	NO	---	
⊖	.106	8	NO	---	

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES .XX .XXX DO NOT SCALE DRAWING			CONTRACT NO.		UNIVERSITY OF CHICAGO ELECTRONICS DEVELOPMENT GROUP			
TREATMENT			APPROVALS	DATE	TITLE			
FINISH			DRAWN M. Bogdan	3/18/2011	PSEC TRAY Analog Card Specification Drawing			
SIMILAR TO			CHECKED M. Bogdan	3/18/2011	SIZE	FSCN NO.	DWG. NO. 2720	REV. A
ACT. WT	CALC. WT		ISSUED		SCALE 1/2		SHEET	

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